# LNJ308G8TRA

Surface Mounting Chip LED

SS Type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	50	mW	
Forward current	I <sub>F</sub>	20	mA	
Pulse forward current *	I <sub>FP</sub>	100	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

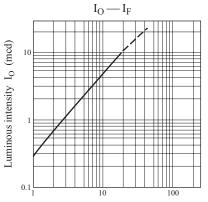
Lighting Color

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

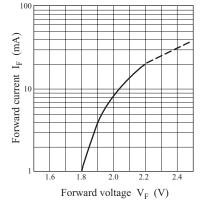
#### Electro-Optical Characteristics $T_a = 25^{\circ}C$

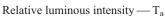
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I <sub>O</sub>	$I_F = 10 \text{ mA}$	2.25	5.0		mcd
Reverse current	I <sub>R</sub>	$V_R = 4 V$			10	μΑ
Forward voltage	V <sub>F</sub>	$I_{\rm F} = 10  {\rm mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 10  {\rm mA}$		565		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 \text{ mA}$		30		nm

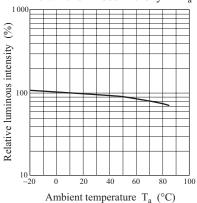
 $I_F - V_F$ 

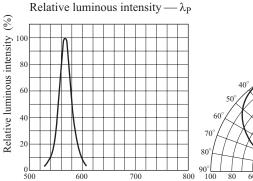


Forward current  $I_F$  (mA)

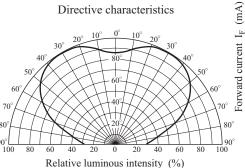


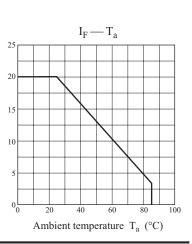






Peak emission wavelength  $\lambda_P$  (nm)

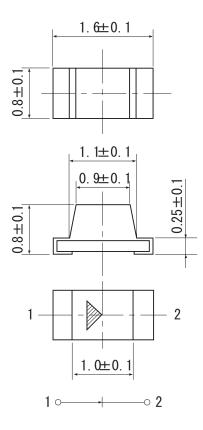




Yellow Green

Package (Unit: mm)

### KLTFTN2K0800



• Pin name

1: Anode

2: Cathode

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